



Bonding market to surpass USD 3.9 billion growth – April 5, 2023

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The key market players are listed in the report with their sales, revenues and strategies are Kulicke & Soffa, Moschip Technologies Ltd, Tata Elxsi Ltd, Shinkawa Ltd, Shibaura Mechatronics, Yamaha Motor Robotics Corporation Co., Fuji Corporation, SPEL Semiconductor Ltd, Panasonic Corporation, SUSS MicroTech SE, ASM Pacific Technology Ltd., Fasford Technology, EV Group, Ruttonsha International Rectifier Ltd, Dixon Technologies (India) Ltd, BE Semiconductor Industries N.V., and others.

Zion Market Research has published a new research report titled “Semiconductor Bonding Market - By Type (Die Bonder, Wafer Bonder, And Flip Chip Bonder), By Application (RF Devices, 3D NAND, CMOS Image Sensors, LED, And MEMS & Sensors), By Process Type (Die-To-Die Bonding, Wafer-To-Wafer Bonding, And Die-To-Wafer Bonding), By Bonding Technology (Die Bonding Technology And Wafer Bonding Technology), And By Region - Global And Regional Industry Overview, Market Intelligence, Comprehensive Analysis, Historical Data, And Forecasts 2023 – 2030” in its research database.

“According to the latest research study, the demand of global Semiconductor Bonding Market size & share in terms of revenue was valued at USD 1.8 billion in 2022 and it is expected to surpass around USD 3.9 billion mark by 2030, growing at a compound annual growth rate (CAGR) of approximately 3.12% during the forecast period 2023 to 2030.”

https://siliconsemiconductor.net/article/116469/Bonding_market_to_surpass_USD_39_billion_growth